

## **Preface to the Special Issue on “1<sup>st</sup> International Congress on Advances in the Packaging Industry - *Product and Process* (API 2015)”**

The 1<sup>st</sup> International Congress on Advances in the Packaging Industry - *Product and Process* (API 2015) was held in Naples (Italy) on 19-20 November 2015. It was organized by the Regional Competence Centre for Technologies (CRdC Tecnologie Scarl, [www.crdctecnologie.it](http://www.crdctecnologie.it)), the Department of Chemical, Materials and Production Engineering of the University of Naples Federico II (DICMaPI, [www.dicmapi.unina.it](http://www.dicmapi.unina.it)), the Department of Industrial Engineering of the University of Salerno (DIIn, [www.diin.unisa.it](http://www.diin.unisa.it)), and the Italian Flexible Packaging Association (Giflex, [www.giflex.it](http://www.giflex.it)).

Reflecting the double soul of the organization, the congress aimed at gathering experts from academia and industry to focus on product and process innovations in flexible packaging technology. The topics were addressed to provide a short, medium and long-term vision on this field with a special emphasis to: chemophysical properties of packaging materials; barrier solutions for flexible packaging; surface treatments and functionalization of packaging substrates; metal and metallized packaging; food packaging safety; inks, coatings, adhesives and their solvents; solvent recovery and after burning; sustainable packaging and processes; risk assessment in the packaging industry; mechanics of films; printing technologies for flexible packaging. API 2015 was a successful event with nearly 180 participants among academic and industry representatives. Results of research, technological development and demonstration activities were presented during the congress. The contributions consisted of 4 key notes and 30 orals, which were organized in 7 successive sections, and 28 posters. They were originated from countries like the USA, China, Belgium, Germany, Hungary, Spain, Switzerland, Turkey, and Italy.

This special issue of the “Journal of Applied Packaging Research” (JAPR) dedicated to the “1<sup>st</sup> International Congress on Advances in the Packaging Industry - *Product and Process* (API 2015)” collects a well-balanced selection of academic and industrial papers presented during the congress. It is intended to provide the readership of the journal with a survey of results and progress recently achieved in the field of flexible packaging. The papers appear in the special issue in chronological order of receipt of contribution.

Sincere thanks go to Prof. Changfeng Ge, JAPR's editor-in-chief: without his enthusiastic spirit of collaboration, this special issue would not have been possible. Efforts of the editorial staff of the journal are also gratefully acknowledged.

The 2<sup>nd</sup> edition of the congress will be held in Italy in 2017 (API 2017).

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